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Fig. 1

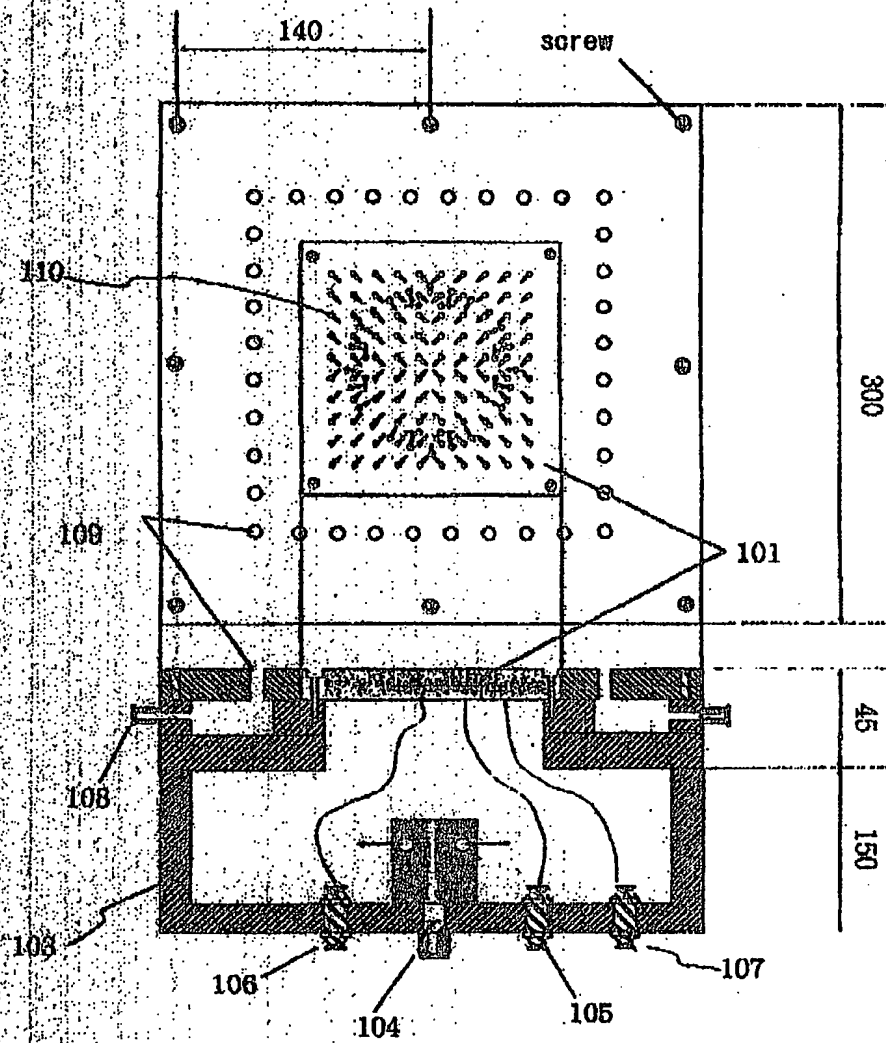
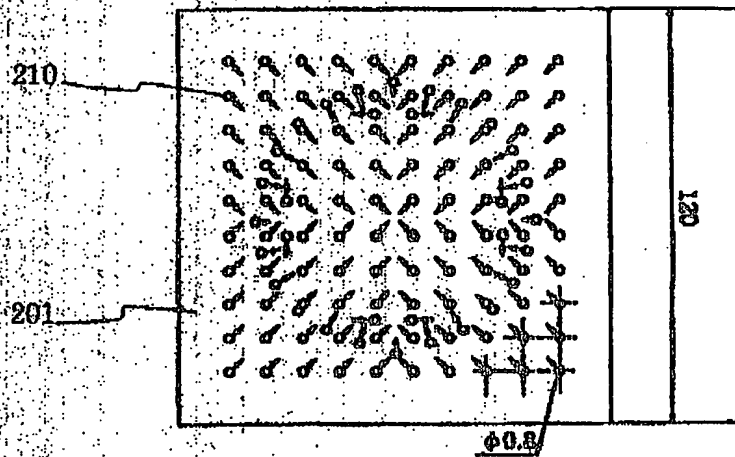


Fig. 2

(a) Detailed view of a floating unit



(b) Form of a fine pore

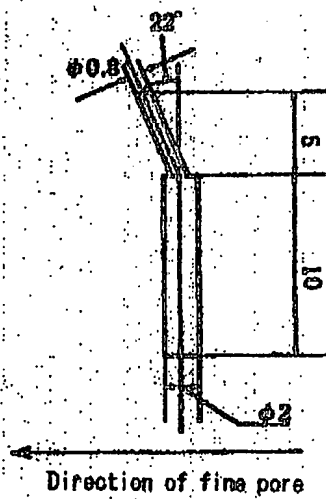
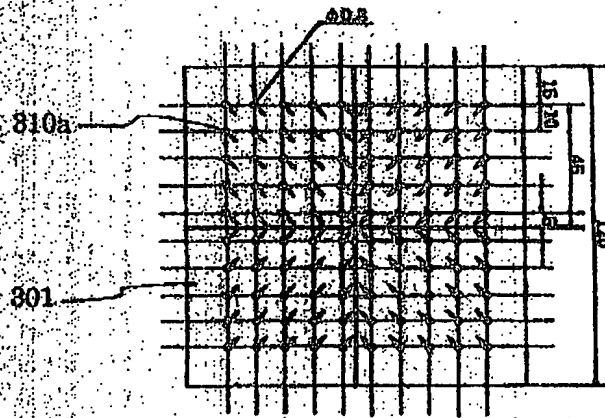
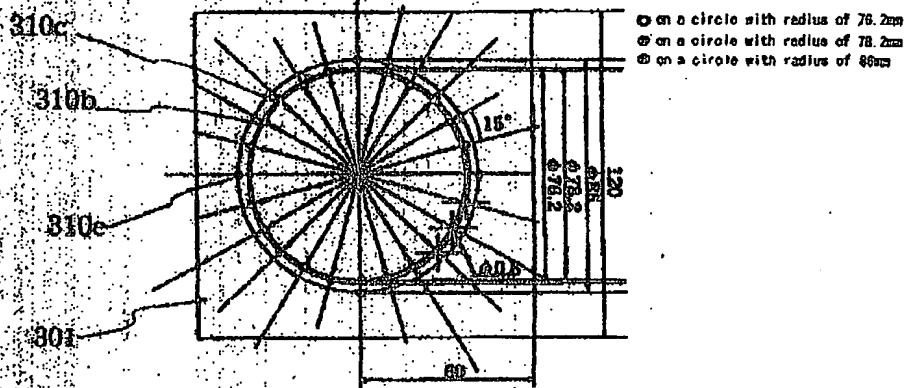


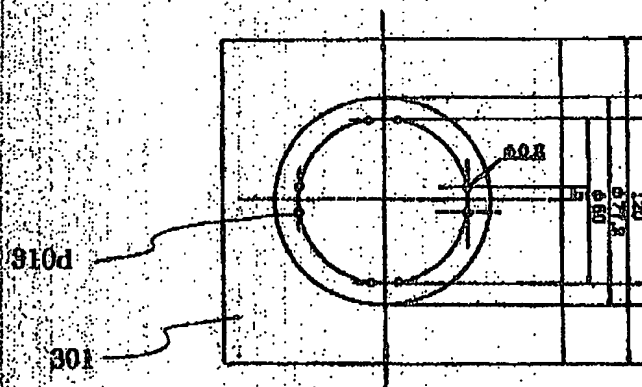
Fig. 3



(a) A group of fine pores for floating unit



(b) A group of fine pores for centering and a group of auxiliary fine pores



(c) A group of fine pores for rotation

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Fig. 4

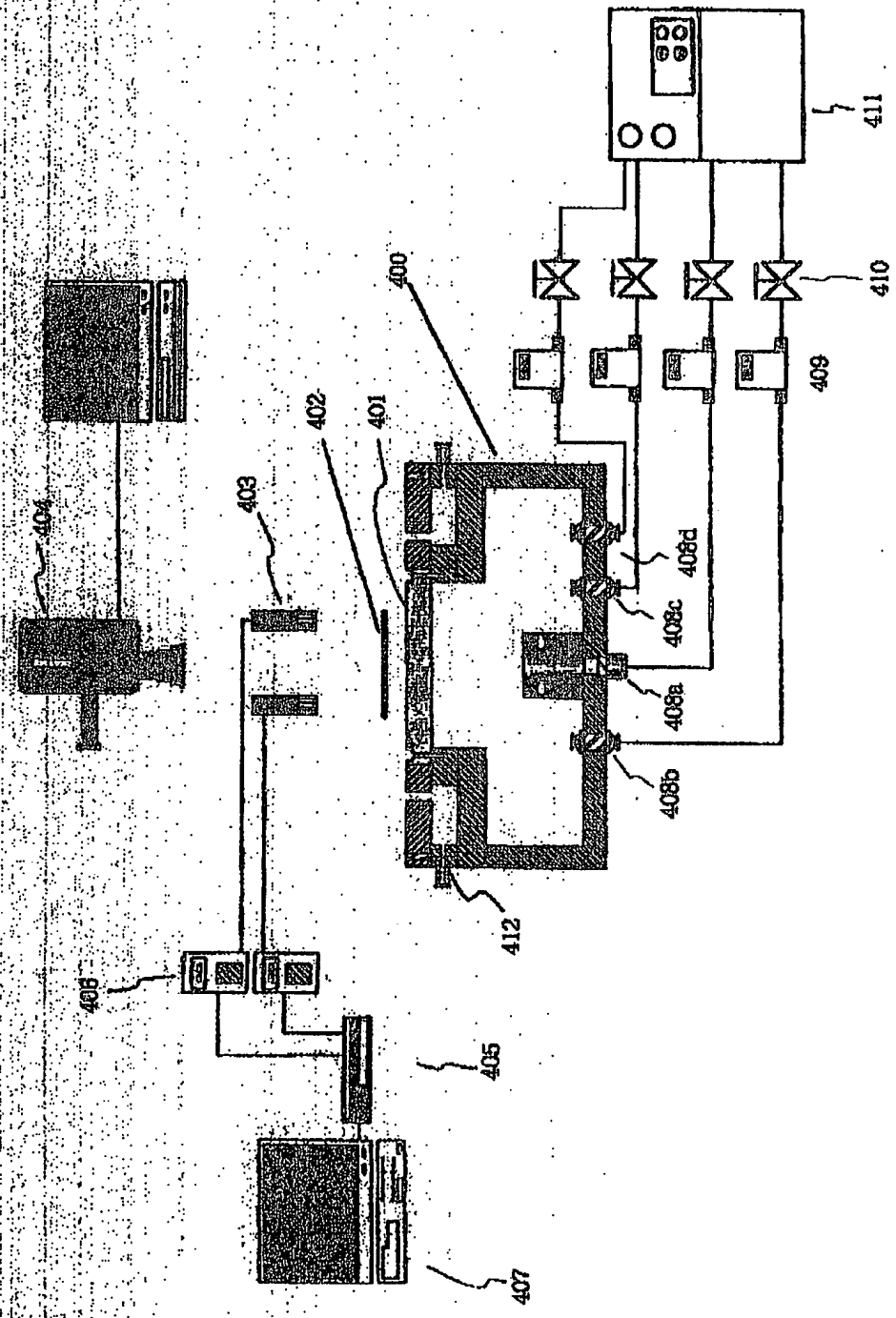
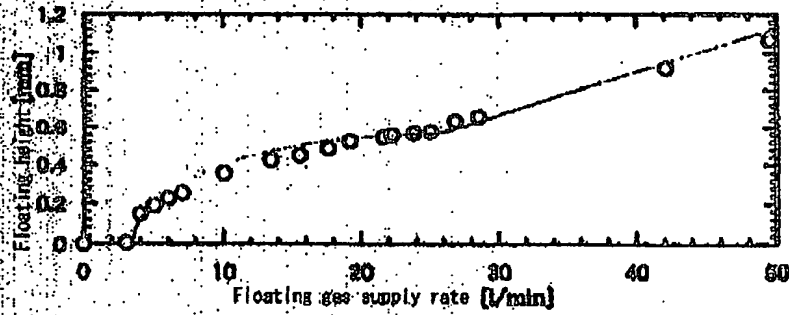
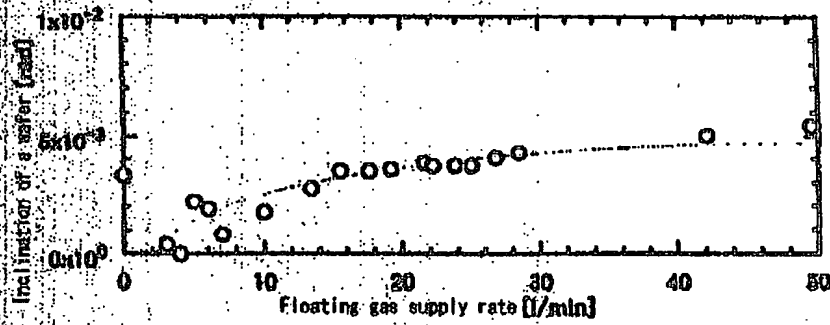


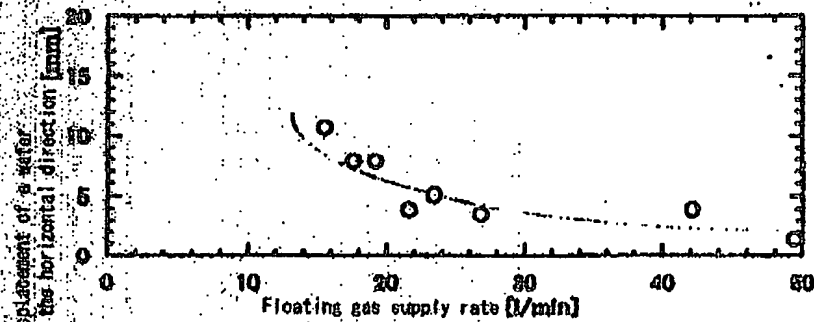
Fig. 5



(a) Influence over a floating height

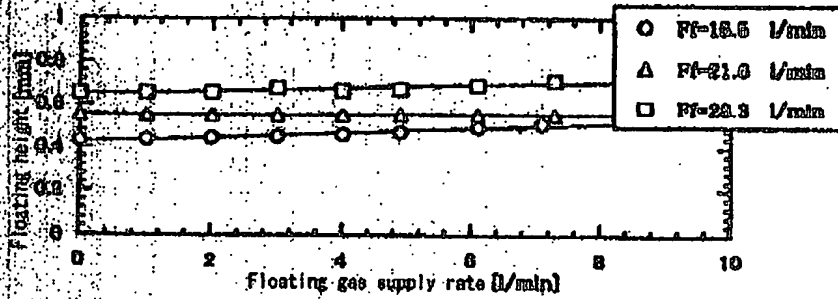


(b) Influence over inclination of a wafer

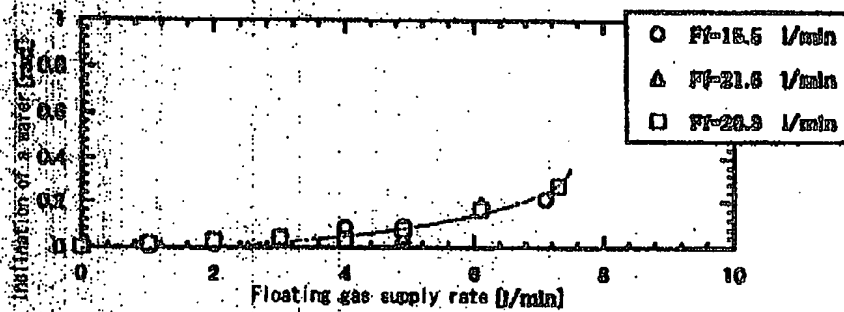


(c) Influence over displacement of a wafer in the horizontal direction

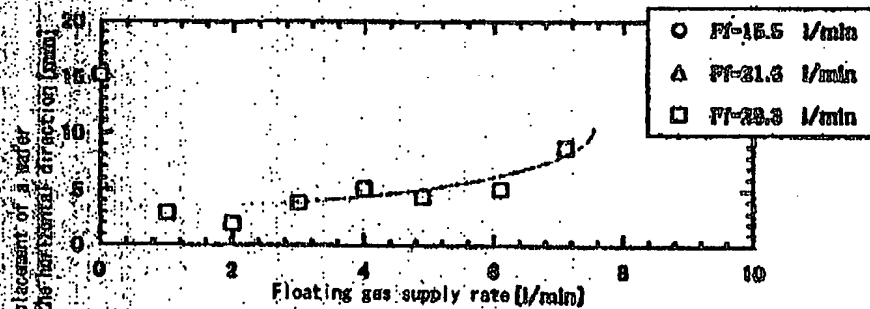
F. 6



(a) Influence over floating height

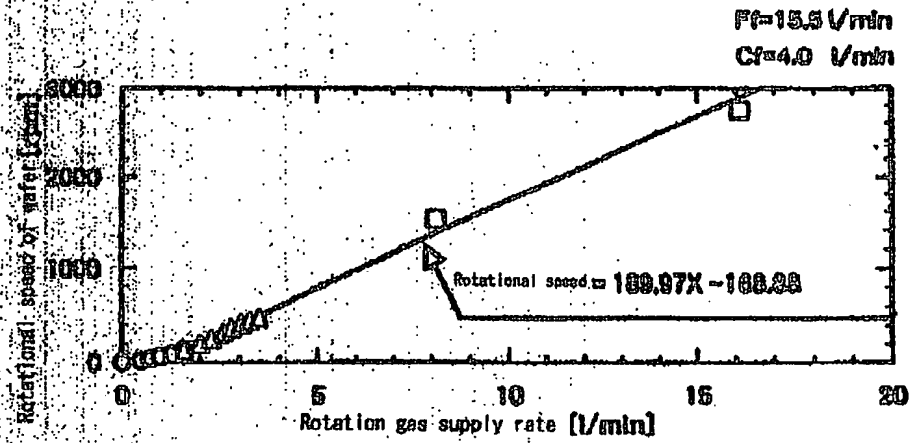


(b) Influence over inclination of a wafer

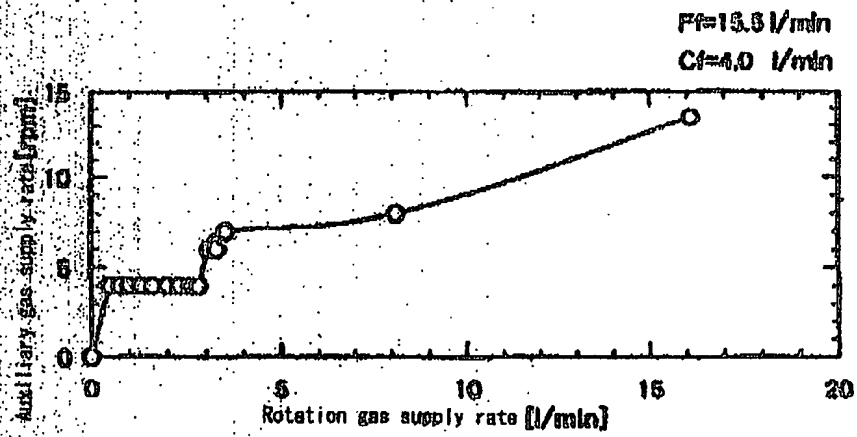


(c) Influence over displacement of a wafer in the horizontal direction

F. 7

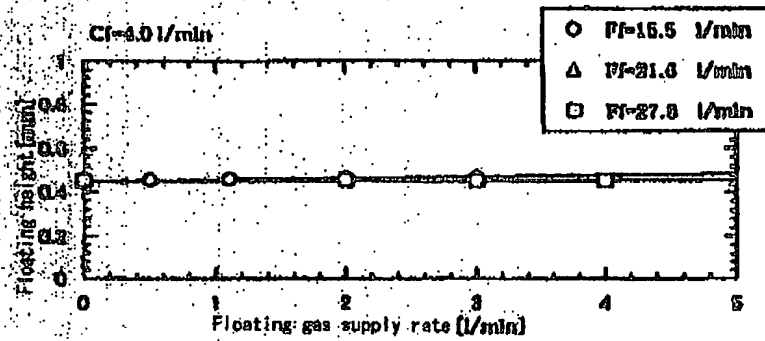


F. 8

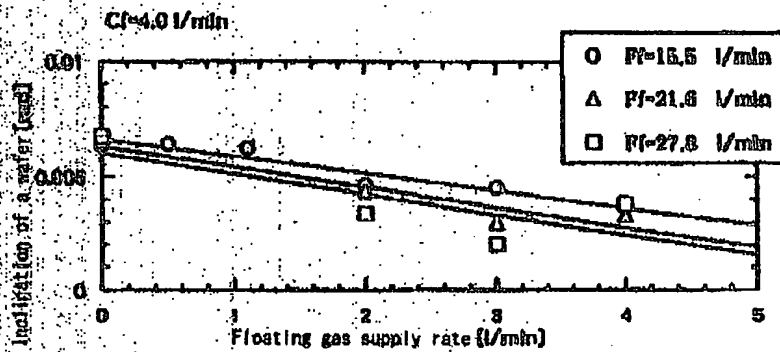




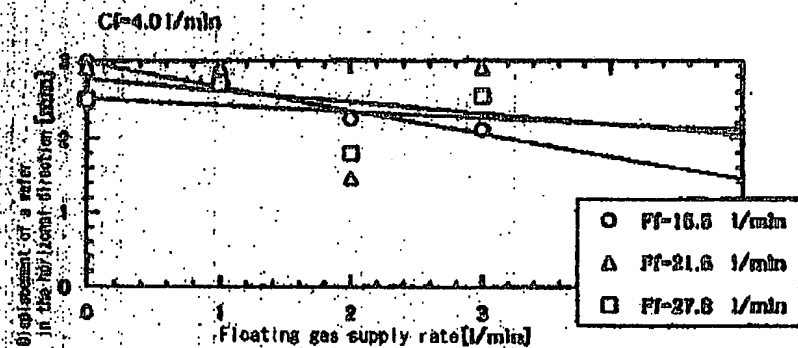
9



(a) Influence over a floating height



(b) Influence over inclination of a wafer



(c) Influence over displacement of a wafer in the horizontal direction

Fig. 10

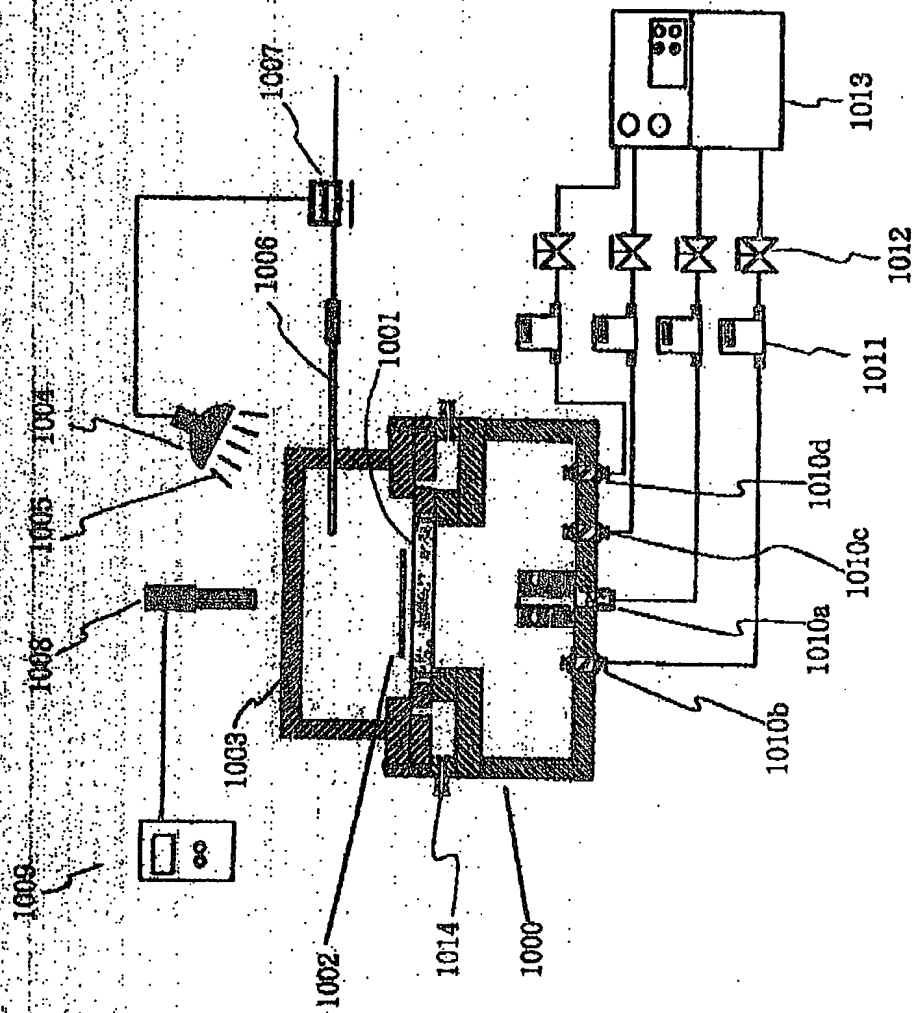
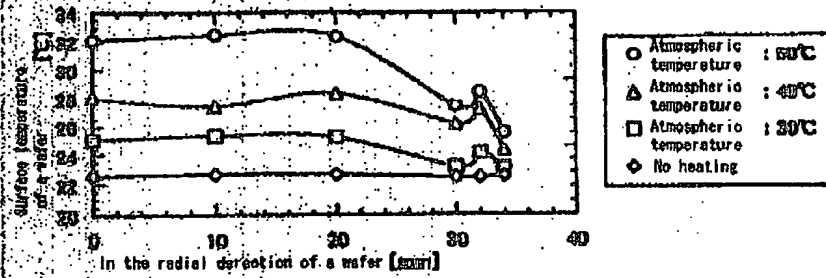


Fig. 11

(a) Temperature gradation on a surface of a wafer (When rotated)



(b) Temperature gradation on a surface of a wafer (When not rotated)

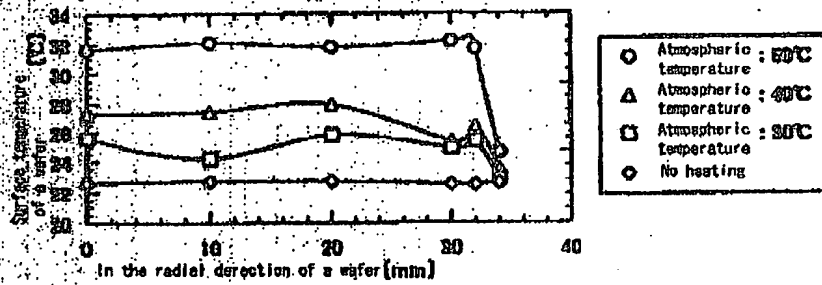


Fig. 12

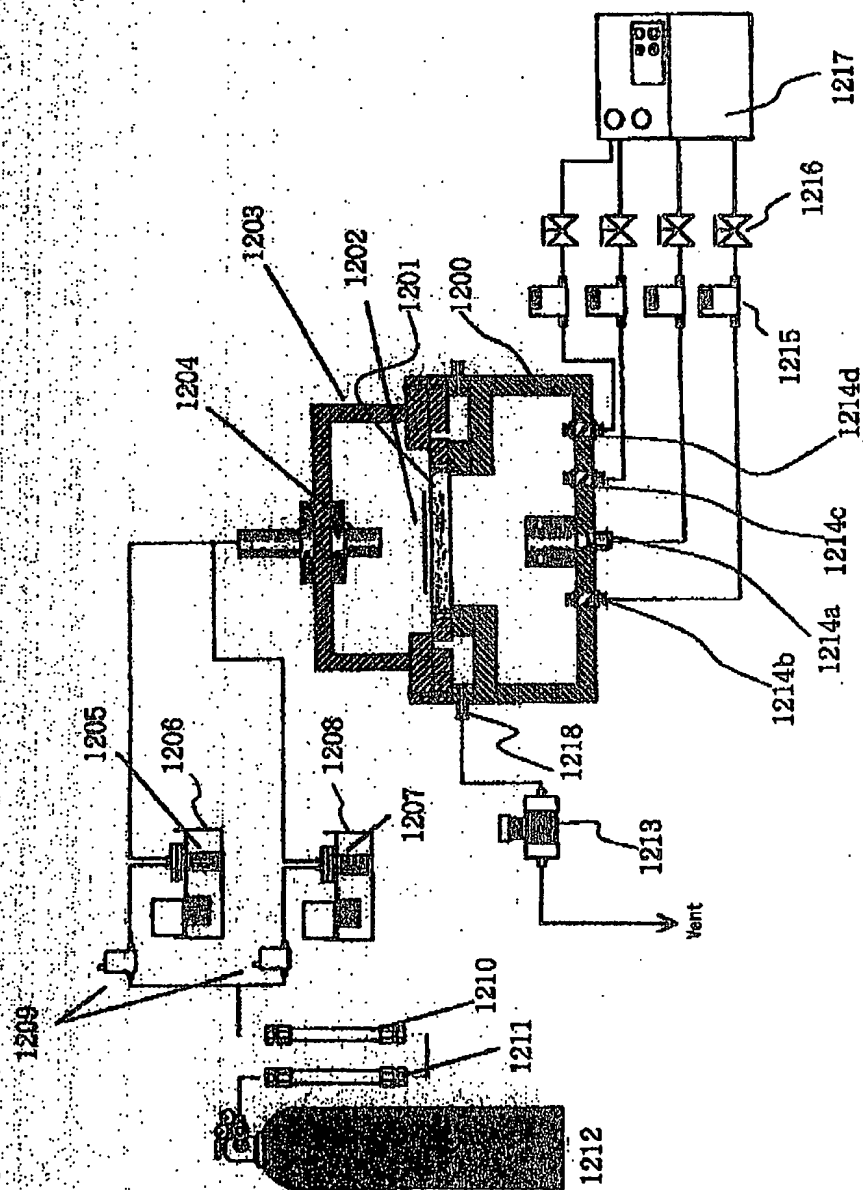


Fig. 13

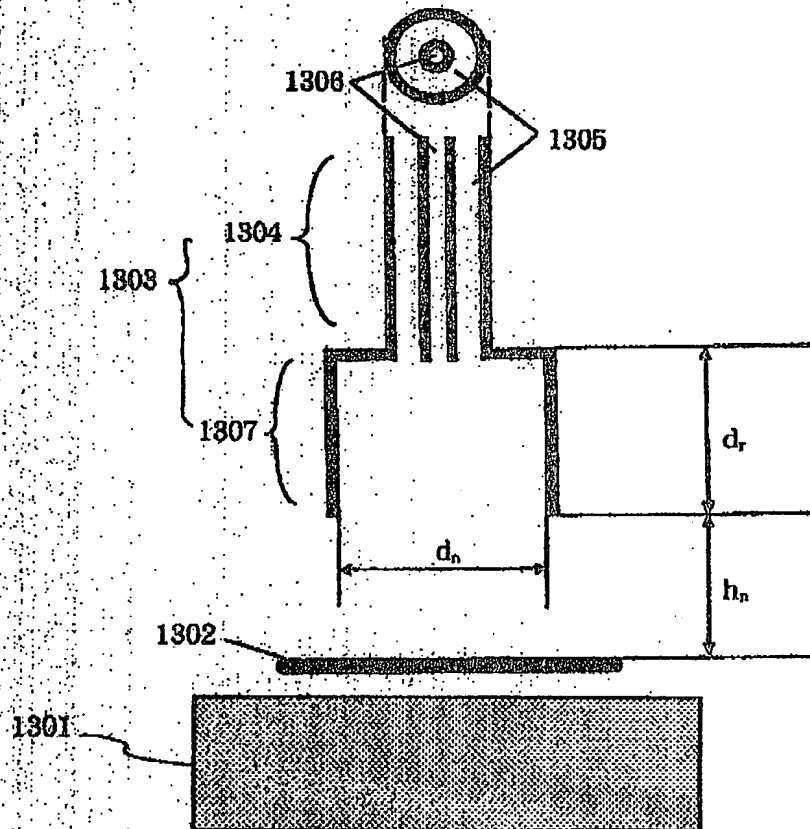


Fig. 14

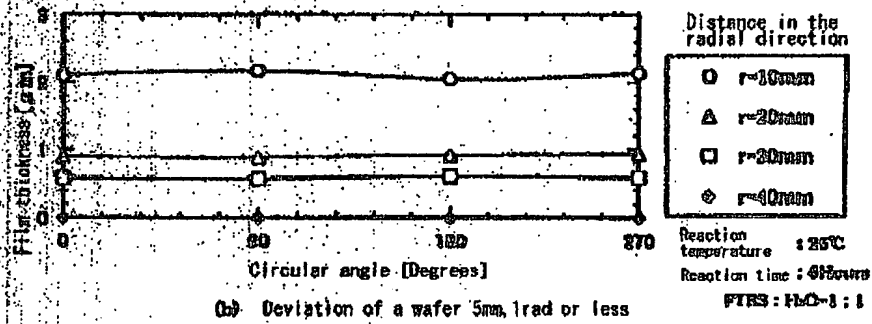
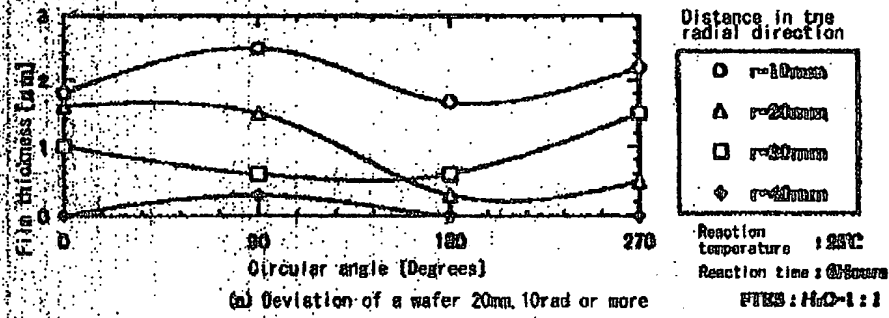
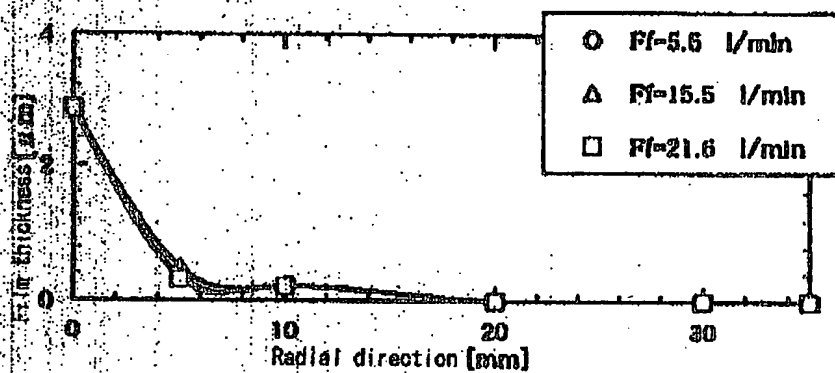
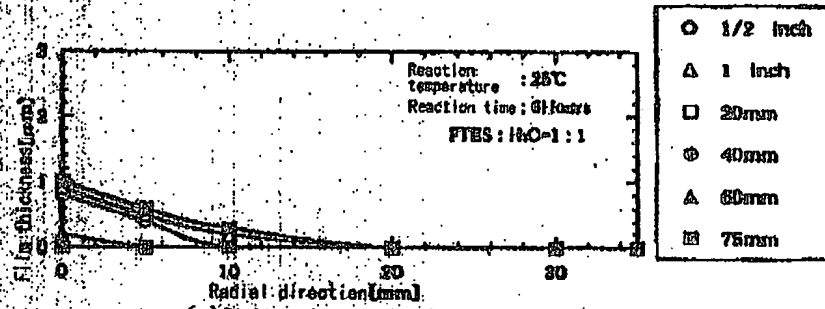


Fig. 15

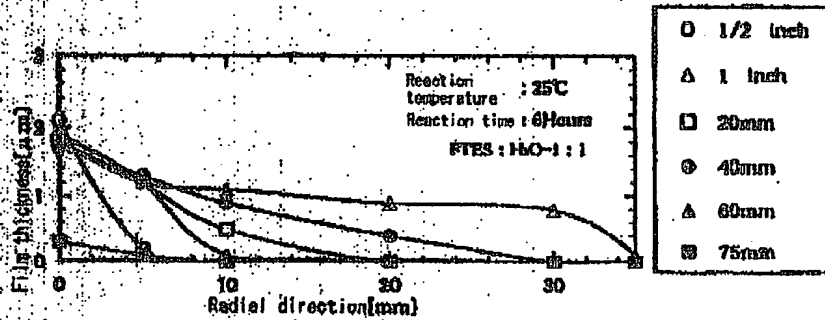
Reaction  
temperature : 25°C  
Reaction time : 6 hours  
FES : H<sub>2</sub>O = 1 : 1



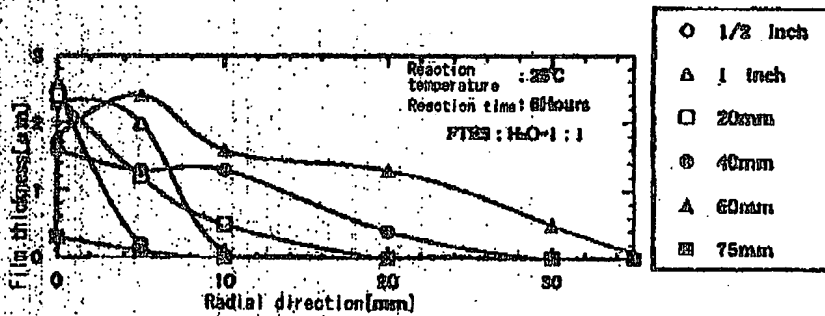
F. 16



(a) Distance between a nozzle tip and a substrate : 5mm



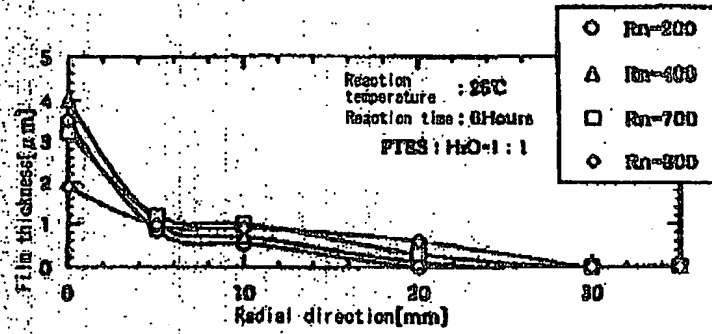
(b) Distance between a nozzle tip and a substrate : 2mm



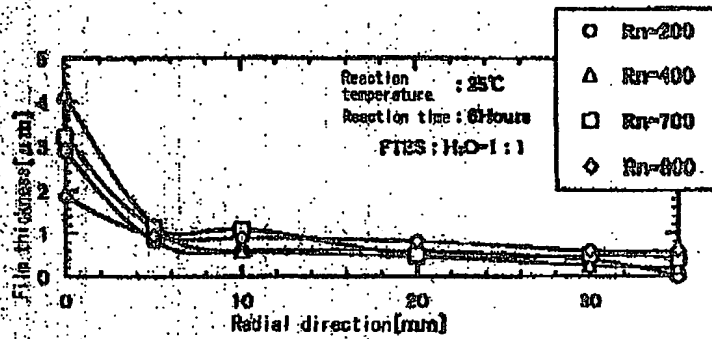
(c) Distance between a nozzle tip and a substrate : 1mm



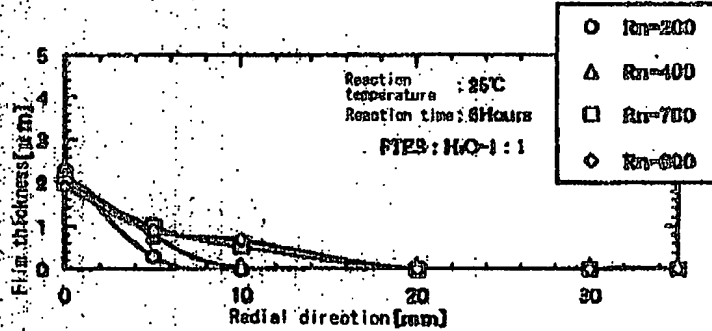
Fig. 17



(a) Distance between a nozzle tip and a substrate : 2mm  
nozzle diameter : 40mm



(b) Distance between a nozzle tip and a substrate : 2mm  
nozzle diameter : 60mm



(c) Distance between a nozzle tip and a substrate : 2mm  
nozzle diameter : 75mm

Fig. 18

